

30V N-Channel Enhancement Mode MOSFET

Description

The AP60N03F/T/P uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 30V I_D =60A

 $R_{DS(ON)} < 8.5 \text{m}\Omega$ @ $V_{GS}=10V$ (Type: $6.0 \text{m}\Omega$)

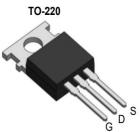
AP60N03F/T/P XXX YYYY

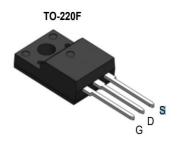
Application

BLDC

Wireless impact

Mobile phone fast charging







Package Marking and Ordering Information

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Product ID	Pack	Marking	Qty(PCS)
AP60N03F	TO-220-3L	AP60N03F XXX YYYY	1000
AP60N03T	TO-263-3L	AP60N03T XXX YYYY	800
AP60N03P	TO-220-3L	AP60N03P XXX YYYY	1000

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	30	V
VGS	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	60	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	40	А
IDM	Pulsed Drain Current ²	92	А
EAS	Single Pulse Avalanche Energy ³	57.8	mJ
IAS	Avalanche Current	34	Α
P _D @T _C =25°C	Total Power Dissipation ⁴	29	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R _θ JA	Thermal Resistance Junction-ambient ¹	62	°C/W
R₀JC	Thermal Resistance Junction-Case ¹	4.32	°C/W





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Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V_{GS} =0 V , I_D =250 u A	30	33		V
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =12A		6.0	8.5	mΩ
ND3(ON)	Static Drain-Source On-INESIStatice	V _{GS} =4.5V , I _D =10A		8.0	13	11152
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.6	2.5	V
△VGS(th)	V _{GS(th)} Temperature Coefficient	VGS-VDS, ID -250UA		-5.8		mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C	I		1	uA
1033		V _{DS} =24V , V _{GS} =0V , T _J =55°C	-		5	
IGSS	Gate-Source Leakage Current	V_{GS} =±20 V , V_{DS} =0 V	I		±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		9.8		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)	V _{DS} =20V , V _{GS} =4.5V , I _D =12A		12.8		
Qgs	Gate-Source Charge			3.3		nC
Qgd	Gate-Drain Charge			6.5		
Td(on)	Turn-On Delay Time			4.5		
Tr	Rise Time	$V_{DD}=12V$, $V_{GS}=10V$,		10.8		no
Td(off)	Turn-Off Delay Time	R_G =3.3Ω I_D =5Α		25.5		ns
T _f	Fall Time			9.6		
Ciss	Input Capacitance			1317		
Coss	Output Capacitance	V_{DS} =15V , V_{GS} =0V , f=1MHz		163		pF
Crss	Reverse Transfer Capacitance			131		
IS	Continuous Source Current ^{1,6}	\/-=\/-=0\/			46	Α
ISM	Pulsed Source Current ^{2,6}	V _G =V _D =0V , Force Current			92	Α
VSD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1	V

Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2_{\times} The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$
- $3 \times$ The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=34A
- $4\$ The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

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Typical Characteristics

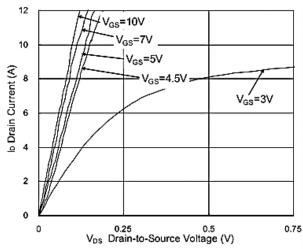
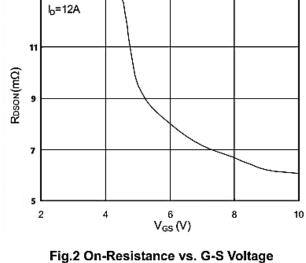


Fig.1 Typical Output Characteristics



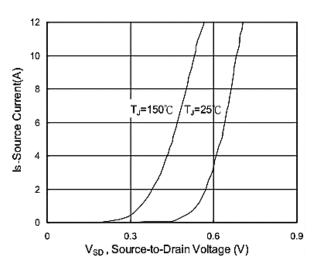


Fig.3 Forward Characteristics of Reverse

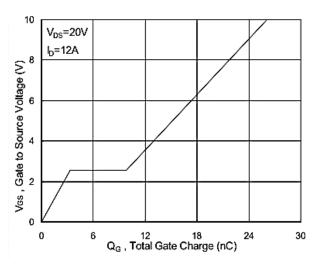


Fig.4 Gate-Charge Characteristics

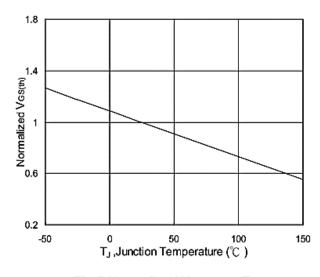


Fig.5 Normalized V_{GS(th)} vs. T_J

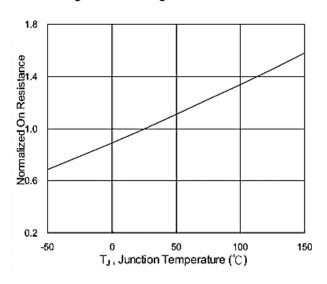
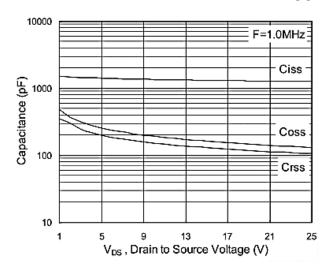


Fig.6 Normalized RDSON vs. TJ

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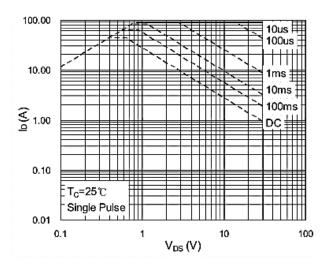


Fig.7 Capacitance

Fig.8 Safe Operating Area

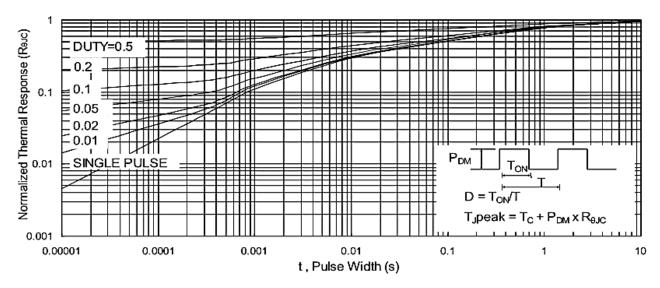


Fig.9 Normalized Maximum Transient Thermal Impedance

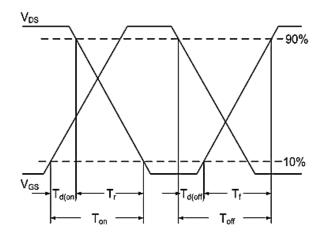


Fig.10 Switching Time Waveform

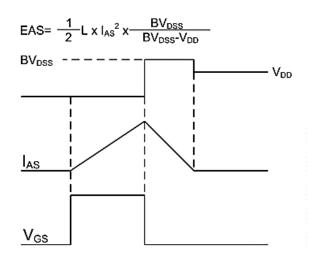
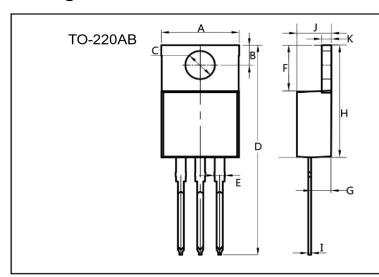


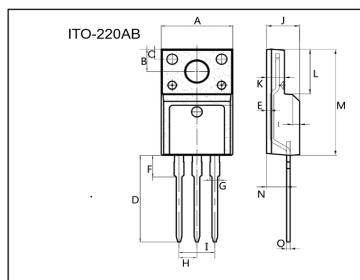
Fig.11 Unclamped Inductive Switching Waveform

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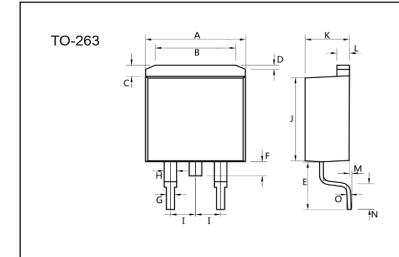
Package Mechanical Data-PDFN5*6-8L-JQ Single



Dim.	Min.	Max.
Α	10.0	10.4
В	2.5	3.0
С	3.5	4.0
D	28.0	30.0
Е	1.1	1.5
F	6.2	6.6
G	2.9	3.3
Н	15.0	16.0
1	0.35	0.45
J	4.3	4.7
K	1.2	1.4
All Dimensions in millimeter		



Dim.	Min.	Max.	
Α	9.9	10.3	
В	2.9	3.5	
С	1.15	1.45	
D	12.75	13.25	
E	0.55	0.75	
F	3.1	3.5	
G	1.25	1.45	
Н	Typ 2.54		
I	Typ 5.08		
J	4.55	4.75	
K	2.4	2. 7	
L	6.35	6.75	
М	15.0	16.0	
N	2.75	3.15	
0	0.45	0.60	
All Dimensions in millimeter			



Dim.	Min. Max.			
Α	10.0	10. 5		
В	7.25	7.75		
С	1.3	1.5		
D	0.55	0.75		
E	5.0	6.0		
F	1.4	1.6		
G	0.75	0.95		
Н	1.15	1.35		
I	Typ 2.54			
J	8.4	8.6		
K	4.4	4.6		
L	1.25	1.45		
М	0.02	0.1		
N	2.4	2.8		
0	0.35	0.45		
All Dimensions in millimeter				